Hybrid Couplers 3dB, 90°

Type PC2025A2700AT00





GENERAL DESCRIPTION

The PC2025A2700AT00 is a RoHS compliant low profile wideband 3dB hybrid coupler which can support mobile applications, including PCS and DCS applications. The power coupler series of components is based on AVX's patented MLO™ technology (US patents 6,987309, 7,068,124) which incorporates lumped elements and micro vias. The resultant designs and finished structures allow for the integration of high Q passives in a low cost high density interconnect component. The PC2025A2700AT00 is a multifunctional component designed for attenuators, phase shifters, LNAs, balance amplifiers and signal distribution. All components are electrically tested prior to tape and reel. Reliability testing is performed to JEDEC and Mil standards. Finishes are available in RoHS compliant NiSn and immersion Au.

FEATURES

- 2.1 2.7 GHz
- Excellent Isolation
- DCS and PCS
- Expansion Matched to PCB Wireless LAN's
- 90° Quadrature
- Surface Mountable
- RoHS Compliant
- Available in Tape and Reel

HOW TO ORDER



APPLICATIONS

• Mobile communications

• Vehicle location systems

• GPS



00 = Standard

Product

LAND GRID ARRAY

ADVANTAGES

Inherent Low Profile

Low Parasitics

Excellent Solderability

Better Heat Dissipation

Packaging Code 1 = Bulk2 = 500 pcs, 7" reel

1

4 = 2000 pcs, 13" reel

ELECTRICAL SPECIFICATIONS*

Frequency (GHz)	Isolation (dB min)	I. L. (dB max)	VSWR	Amplitude Balance (dB max)	Phase Balance (Degrees)	Max Power (Watts)	Operating Temperature (°C)
2.1 – 2.7	18	0.25	1.29	±0.35	±3°	30	-55 to +85

* Specification based on performance of component assembled properly on printed circuit board with 50Ω nominal impedance.

QUALITY INSPECTION

Finished parts are 100% tested for electrical parameters and visual characteristics.

TERMINATION

Finishes include NiSn and immersion Au, All finishes compatible with automatic soldering technologies: Pb free reflow, wave soldering, vapor phase and manual.

TOP VIEW



	mm (inches)
L	6.35 (0.25)
W	5.08 (0.20)
Т	1.0 (0.04)

OPERATING	
TEMPERATUR	RE

- 55°C to +85°C

KIDERA | The Important Information/Disclaimer is incorporated in the catalog where these specifications came from or available online at www.avx.com/disclaimer/ by reference and should be reviewed in full before placing any order. ANAX (



MECHANICAL OUTLINE



TYPICAL PERFORMANCE: 2.1 TO 2.7 GHZ



Amplitude Balance





KY<u>OCERa</u>

Phase Balance







Isolation



KUCCERA available online at www.avx.com/disclaimer/ by reference and should be reviewed in full before placing any order.



HYBRID COUPLER TEST JIGS

GENERAL DESCRIPTION

These jigs are designed for testing the 3dB Hybrid Couplers using a Vector Network Analyzer. They consist of a dielectric substrate, having Cu microstrips as conducting lines and a bottom ground plane located at a distance of 0.254mm from the microstrips.

The substrate used is Taconic RF 35 0100. The connectors are SMA type (female), 'Johnson Components Inc.' Product

MOUNTING AND MEASUREMENT PROCEDURE

MLO[™] hybrid couplers require a 50Ω transmission lines leading to and from all of the RF ports. Proper grounding is required in order to ensure optimal device performance.

All of the MLO[™] components utilize castellated interconnects which allow for high yield assembly, expansion matched and halogen free dielectrics.

The MLO™ hybrid coupler is a symmetrical device. When a port is designated as the input, automatically the two output and isolated ports are defined. For example, if the input port for a device was selected to be Pin 1, Pin 2 is automatically the isolated port, Pin 4 is the 0 degree reference output port, and Pin 3 is the output port which "lags" behind the reference output port by 90 degrees. Similarly, if Pin 3 was to be selected as the input port, the adjacent port on the long side (Pin 4) is the isolated port, the adjacent port on the short side (Pin 2) is the 0 degree output port, and the opposite port (Pin 1) is the 90 degree output port.

PIN: I42-070I-84I. Both a measurement jig and a calibration jig are provided. The calibration jig is designed for a full 2port calibration, and consists of an open line, short line and through line. LOAD calibration can be done by a 502 SMA termination.

PIN CONFIGURATION

The PC2025A2700 part has an orientation marker to denote Pin 1. Once port one is determined the other ports are As defined: See the chart below for clarification:



Configuration	Pin 1	Pin 2	Pin 3	Pin 4
Splitter	Input	Isolated	-3dB ∠θ-90	-3dB ∠θ
Splitter	Isolated	Input	-3dB ∠θ	-3dB ∠θ-90
Splitter	-3dB ∠θ-90	-3dB ∠θ	Input	Isolated
Splitter	-3dB ∠θ	-3dB ∠θ-90	Isolated	Input
*Combiner	A ∠θ-90	A∠θ	Isolated	Output
*Combiner	A∠θ	A ∠θ-90	Output	Isolated
*Combiner	Isolated	Output	A ∠θ-90	A∠θ
*Combiner	Output	Isolated	A∠θ	A ∠θ-90

*Note: "A" is the amplitude of the applied signals. When two quadrature signals with equal amplitudes are applied to the coupler as described they will combine at the output port.

MEASUREMENT PROCEDURE

Measurement Jig

Connector 1



Connector 4

Connector 3



Calibration Jig



KIDERA | The Important Information/Disclaimer is incorporated in the catalog where these specifications came from or available online at www.avx.com/disclaimer/ by reference and should be reviewed in full before placing any order. 1 AVAX



AUTOMATED SMT ASSEMBLY

The following section describes the guidelines for automated SMT assembly of MLO[™] RF devices which are typically Land Grid Array (LGA) packages or side termination SMT packages.

Control of solder and solder paste volume is critical for

surface mount assembly of MLO[™] RF devices onto the PCB. Stencil thickness and aperture openings should be adjusted according to the optimal solder volume. The following are general recommendations for SMT mounting of MLO[™] devices onto the PCB.

SMT REFLOW PROFILE

Common IR or convection reflow SMT processes shall be used for the assembly. Standard SMT reflow profiles, for eutectic and Pb free solders, can be used to surface mount the MLO[™] devices onto the PCB. In all cases, a temperature gradient of 3°C/sec, or less, should be maintained to prevent warpage of the package and to ensure that all joints reflow properly. Additional soak time and slower preheating time may be required to improve the out-gassing of solder paste. In addition, the reflow profile depends on the PCB density and the type of solder paste used. Standard no-clean solder paste is generally recommended. If another type of flux is used, complete removal of flux residual may be necessary. Example of a typical lead free reflow profile is shown below:



Profile Parameter	Pb free, Convection, IR/Convection		
Ramp-up rate (Tsmax to Tp)	3°C/second max.		
Preheat temperature (Ts min to Ts max)	150°C to 200°C		
Preheat time (ts)	60 – 180 seconds		
Time above T _L , 217°C (t _L)	60 – 120 seconds		
Peak temperature (Tp)	260°C		
Time within 5°C of peak temperature (tp)	10 – 20 seconds		
Ramp-down rate	4°C/second max.		
Time 25°C to peak temperature	6 minutes max.		



RECOMMENDED PAD LAYOUT





Dimensions are in mm (inches)

KUDEERA The Important Information/Disclaimer is incorporated in the catalog where these specifications came from or available online at www.avx.com/disclaimer/ by reference and should be reviewed in full before placing any order.